Partnership in Solder Technology Innovation

### R Lead-Free Solder Paste PF629-P25

#### Rev. 2017/06/12 Ver.02-01

### **BASIC OVERVIEW**



SnAg0.3Cu0.7 Solder Paste Halide Free No Clean

### **APPLICATIONS**

Universal Lead-Free SMD Solder Paste Wide Range of Applications and PCB designs

### **FEATURES**

Appearance	Gray paste	w/o visib					
Alloy Composition	Sn/Ag0.3/C	u0.7	JIS-Z-3282				
Melting Point	217~226 °C						
Particle Size	(Type 3)	+45µm	< 1%	, - 20µm	< 10%	J-STD-005	
	(Type 4)	+38µm	< 1%	, - 20µm	< 10%		
Powder Shape	Spherical						
Flux Content	11.5 ± 1.0 wt%					JIS-Z-3197, 8.1.2	
Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)					JIS-Z-3284 Annex 6	
Flux Type	ROLO					J-STD-004	

### Alloy Detail Composition

(Sn)	(Ag)	(Cu)	(Ni)	(Ge)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)	(Pb)
	0.2~	0.5~	0~	0~	0.001	0.001	0.05	0.02	0.03	0.06	0.002	0.05
REM.	0.4	0.9	0.01	0.01	MAX	MAX	MAX	MAX	MAX	MAX	MAX	MAX
Patent No.: U.S Patent No. 6179935B1, Germany Patent No.19816671C2 (wt%)												

Scan Code for Solder Paste Documents

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### **PERFORMANCE & RELIABILITY**

Copper Plate Corrosion Test	Pass	IPC-TM-650, 2.6.15	
Halogen Content Test	ROLO	BS EN14582	
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32	
Viscosity Test (25°C,10 rpm)	200 ± 30 Pa.s	JIS-Z-3284. Annex 6	
Spreading Test	> 70%	JIS-Z-3197, 8.3.1.1	
Tackiness Test (gf)	> 130 (8hr)	JIS-Z-3284. Annex 9	
Slump Test	Pass	JIS-Z-3284. Annex 7,8	
Solder Ball Test	Pass	JIS-Z-3284. Annex 11	

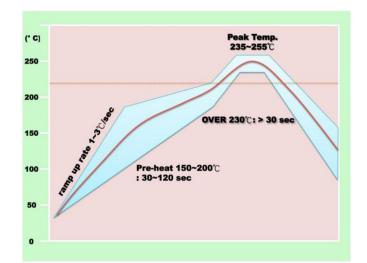
S.I.R. Test		Pass	IPC-TM-650, 2.6.3.3	
Electro Migration Test	٠	Pass	IPC-TM-650, 2.6.14.1	

▲ Test Conditions : 85 °C, 85% RH for 168hrs

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Test Conditions: 65°C, 88.5% RH for 596 hrs

### **RECOMMENDED REFLOW PROFILE**



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Ramp Up Rate (30-150°C):	1.0-3.0 °C/sec
Pre-heating Time (150-200°C):	30-120 sec
Time Period Above 230°C:	>30 sec
Peak Temperature:	235-255 °C
Ramp Down Cooling Rate:	1.0-6.0 °C/sec

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.

Pre-heating Time (150-200°C):	30-120 sec
Time Period Above 230°C:	>30 sec
Peak Temperature:	235-255 °C
Ramp Down Cooling Rate:	1.0-6.0 °C/sec



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### **STORAGE & HANDLING:**

- Refrigerate the solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away of direct sunlight.
- Allow the paste to reach defined printing temperature (room temperature) for 3-4 hrs. Do not heat up the solder paste rapidly.
- For jars packaging, mix the solder paste before use for 1-3 mins by plastic spatula.
- It is recommended to finish fresh paste within 24 hrs. Do not store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hour, remove the remained paste from stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60% .

Note: For more information, please refer to solder paste application guideline sheet

### **HOW TO ORDER**

## PF629 – P25 – T3 – 500

Solder Alloy PF629 = SnAg0.3Cu0.7 Flux P25 = ROL0

Particle Size T3 = 20-45μm T4 = 20-38μm

Weight / Packaging 30 = syringe 30g 100 = syringe 100g 150 = syringe 150g 250 = plastic jar 250g 500 = plastic jar 500g 600 = small cartridge 600g 1200 = large cartridge 1200g



SYRINGE

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